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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: DAVID J. CORISIS ET AL. § Group Art Unit: 2835
Serial No.: 09/152,659 §
Filed: September 14, 1998 § Examiner: B. Chervinsky
For: INTEGRATED CIRCUIT PACKAGE § Atty. Dkt. No.: MCT.0039D2US
SUPPORT SYSTEM §

Commissioner of Patents and Trademarks
Washington, DC 20231

REPLY TO PAPER NO. 6

Dear Sir:

In response to the office action mailed October 24, 2000, please amend the above-referenced patent application as follows:

In the Drawings:

Please make the changes indicated in red in the attached sheet of figures.

In the Claims:

Please amend claim 33 as follows:

33. (Amended) An electronic device, comprising:
a plurality of integrated circuit packages;
a contact surface electrically connected to each of said packages; and
a support arranged to engage each of said packages at a point spaced above said surface to prevent movement of said packages relative to said surface.

Please amend claim 44 as follows:

44. (Amended) The device of claim 43, wherein said support is made of plastic foam with a plurality of slots formed therein, each slot sized to resiliently engage one of said modules.

REMARKS

Each of the objections to form has been cured. As agreed in the interview on October 16, 2000, recorded on paper no. 6, the Interview Summary indicates the applicant agreed to amend claim 35 in order to correct the §112 issue in the claim.

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